

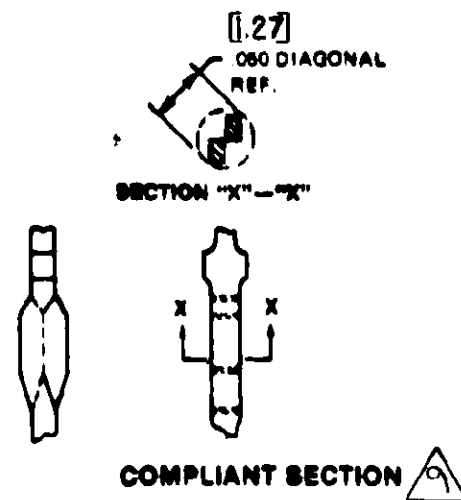
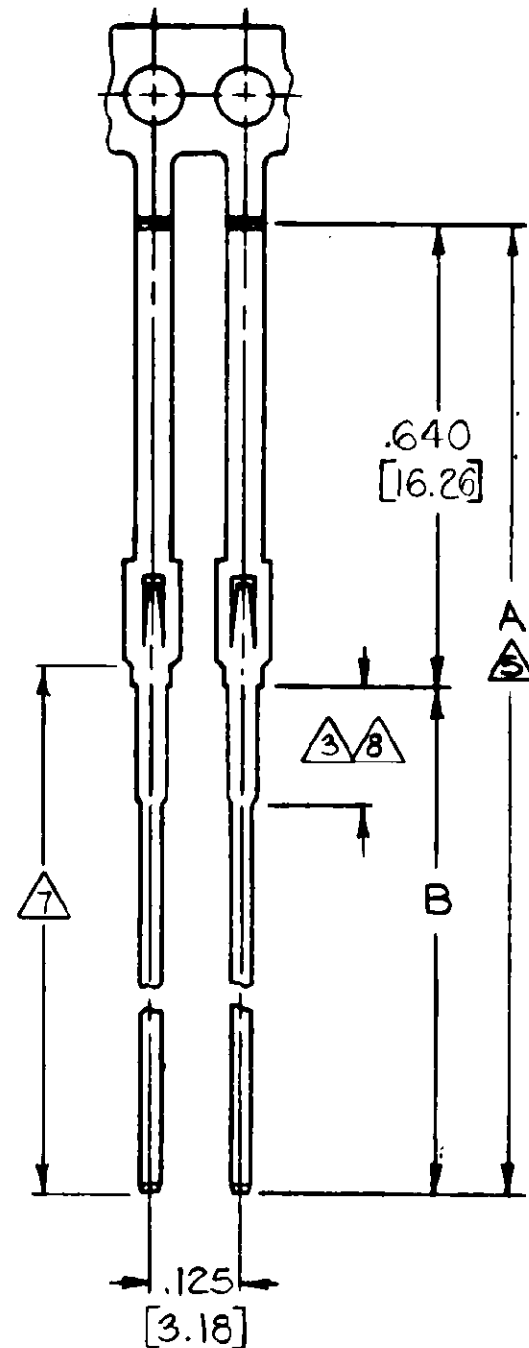
© COPYRIGHT 1981 BY AMP INCORPORATED, HARRISBURG, PA.
ALL INTERNATIONAL RIGHTS RESERVED. AMP INCORPORATED PRODUCTS
COVERED BY U. S. AND FOREIGN PATENTS AND/OR PATENTS PENDING.

REVISIONS					
P	F	ZONE	LTR	DESCRIPTION	DATE
					APPROVED
		C		ECO-20-000961	20JAN20
					HL

PRE-NOTCH FOR BREAK-OFF
AT ASSEMBLY

[2.54]
.100
CONTACT AREA

.025 SQ
[0.64]



OBSOLETE
OBSOLETE
OBSOLETE

1. FOR APPLICATION IN .093/.125 THK. P.C. BOARDS
2. POST DIAGONAL .0315/.0345 [0.80/0.88]
3. COMPLIANT SECTION (SEE DETAIL)
4. ALL DIMENSIONS ARE REFERENCE UNLESS OTHERWISE NOTED
5. NICKEL PLATE .000100 MIN. THK.
6. GOLD PLATE .000075 MIN. THK. OVER NICKEL PLATE
7. SOLDER PLATE .000030 MIN. THK. OVER NICKEL PLATE
8. GOLD PLATE .000005 MIN. THK. OVER NICKEL PLATE

REQUIRED DRILL	DRILLED HOLE DIA ± .0010	PLATING	HOLE DIA	COPPER	PAD DIA
NO. 56	.0465	COPPER Pb/SN AFTER PL AFTER REFLOW	.038/.044	.037/.044	150 KNDP MAX

RECOMMENDED HOLE SIZE

10. MATTE TIN PLATE .000030 MIN THK OVER NICKEL PLATE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ON: DECIMALS ± .005 ANGLES ± 1°		CONTRACT NO		NAME	
MATERIAL		DR <i>Craig Pierce</i> 4-6-81		TYCO ELECTRONICS	
BERYLLIUM COPPER (QQ-C-533)		CHK		CONTACT, AMP PACE	
FINISH NICKEL PLATE PER: QQ-N-290 GOLD PLATE PER MIL-G-45204		APPD		.125 x .125 G	
		APPD		SIZE CODE IDENT NO DRAWING NO	
		DSGN APPD		C 00779 118754	
		OTHER APPD		SCALE SHEET	

CUSTOMER DRAWING